

## Nextreme Names Stephen Brooks as Director of Manufacturing to Facilitate Volume Production

*Nextreme to ramp-up volume manufacturing to meet flip chip market demands*

**Research Triangle Park, N.C. (November 7, 2007)** — Nextreme Thermal Solutions™, a manufacturer of microscale thermal and power management products for the electronics industry, has appointed Stephen Brooks as Director of Manufacturing. Mr. Brooks has more than 24 years of experience in planning, establishing and managing the transition of high-technology companies from R&D to volume manufacturing.



*Stephen Brooks*

Prior to joining Nextreme, he served as the Director of Operations at Amkor Technology in Morrisville, NC. Under Mr. Brooks' leadership, Amkor scaled its back-end flip chip solder bumping capability from zero to a multi-million unit-per-month manufacturing operation within one year of initiation.

As Director of Manufacturing at Nextreme, Mr. Brooks will coordinate Nextreme's move into its new 14,000 square-foot, state-of-the art facility and establish scalable and repeatable volume manufacturing systems for its recently announced Thermal Copper Pillar Bump technology.

"Steve's experience in scaling flip chip manufacturing is a perfect fit for where we are heading with Nextreme," said Jim Mundell, Chief Operating Officer of Nextreme. "His leadership will enable us to construct and ramp a world class manufacturing facility to meet the growing demands from customers who are evaluating our flip chip, thermal and power management products for their cooling and power generation applications."

The flip chip market is one of the largest and fastest growing semiconductor packaging industry market segments. Potential flip chip applications for Nextreme's thermal bump include microprocessors, display drivers, chip sets, RF devices, medical devices, watches, smartcards and analog/mixed signal devices.

Mr. Brooks has also served as Director of Operations with JDS Uniphase - formerly Cronos Integrated Microsystems - where he was responsible for establishing a new MEMS (micro-electro-mechanical-systems) wafer fabrication facility in North Carolina, which at the time was the largest dedicated MEMS wafer production facility worldwide. Prior to Cronos, Mr. Brooks held multiple management positions in manufacturing and business operations during his 15 years at Mitsubishi Semiconductor's DRAM

production facility in North Carolina. He spent more than two years working in Mitsubishi's microelectronics manufacturing operations in Osaka and Kumamoto Japan. Mr. Brooks has extensive experience in the preparation, construction and operation of ISO9001 and TL9000 certified production facilities for VLSI wafer fabrication, MEMS wafer fabrication, IC assembly, IC test, SMT assembly, chip scale packaging (CSP), and die level processing.

Stephen is a North Carolina native and attended North Carolina State University in Raleigh.

For more information, contact Nextreme at 3040 Cornwallis Road, P.O. Box 13981, Research Triangle Park, NC 27709-3981; call (919)-990-8300; e-mail [info@nextreme.com](mailto:info@nextreme.com); or go to [www.nextreme.com](http://www.nextreme.com).

#### **About Nextreme Thermal Solutions, Inc.**

Nextreme Thermal Solutions designs and manufactures microscale thermal and power management products that provide chip, module and system-level solutions for the semiconductor, photonics, consumer, automotive and defense/aerospace industries. The company has developed embedded cooling and power generation capabilities for the widely accepted copper pillar bumping process used in high-volume electronic packaging. Nextreme's breakthrough addresses the most challenging thermal and power management constraints in electronics today, and delivers the only fully-scalable technology solution by leveraging the existing, high-volume flip chip manufacturing infrastructure. By minimizing the need for manufacturing changes and focusing on developing a seamless design-in solution, Nextreme will change the future of thermal and power management for the entire electronics industry.

Nextreme is managed by an experienced start-up team and world-renowned experts in electronics, thermal management and pillar bump technology. The company has 38 employees and is based in Research Triangle Park, North Carolina.

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